Serial No.: 10/045,783 Filed: 01/12/2002

For: Method of Making a Wafer Level Chip Scale Package

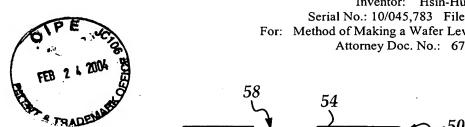
Attorney Doc. No.: 67,200-591

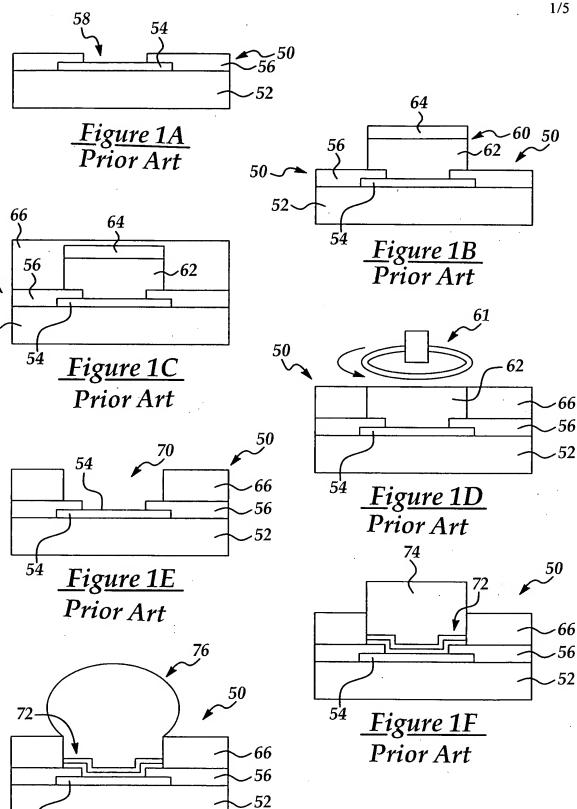


*50* 

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Figure 1G





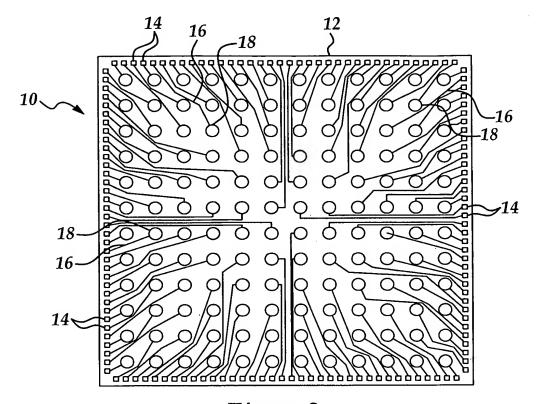
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Inventor: Hsin-Hui Lee

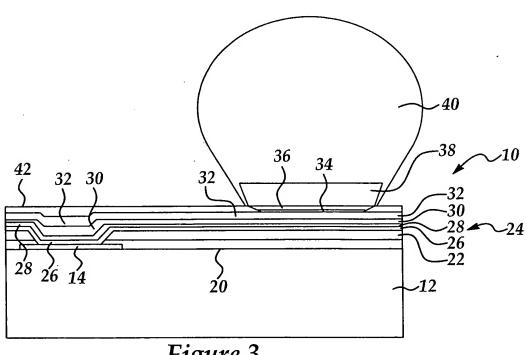
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<u>Figure 2</u> Prior Art



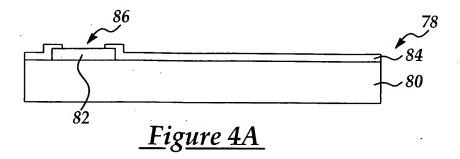
<u>Figure 3</u> Prior Art

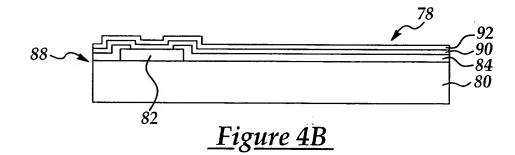
Inventor: Hsin-Hui Lee Serial No.: 10/045,783 Filed: 01/12/2002

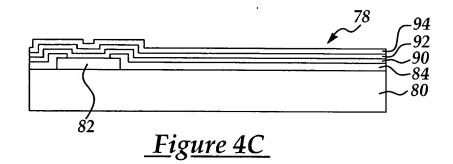
For: Method of Making a Wafer Level Chip Scale Package

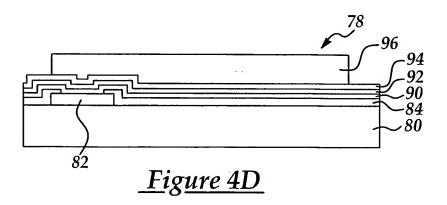


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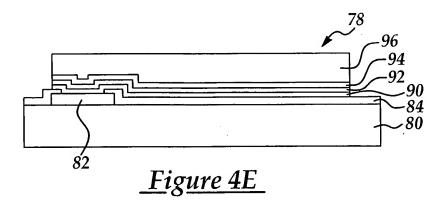


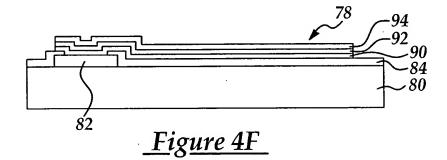


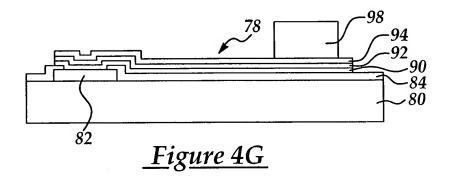
Attorney Doc. No.: 67,200-591

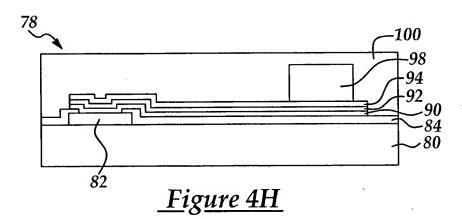


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